# **Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

#### **Listing of Claims:**

#### 1.-7. (Canceled)

8. (Currently Amended) A structure formed in a substrate of monolithic semiconductor material, the structure comprising:

At least one trench formed in the substrate, the at least one trench having an open top and an open bottom, and a coating on the lateral walls of the at least one trench with material resistant to etching:

a cavity having walls <u>and a closed bottom</u> formed below each at least one trench and having an open top in communication with the open bottom of the at least one trench, and a coating on the walls <u>and closed bottom</u> of the cavity with material inhibiting epitaxial growth; and

an epitaxial layer of semiconductor material formed on the substrate to cover the open top of the at least one trench and <u>an epitaxial growth-portion</u> formed in the at least one trench to fill the at least one trench and to encase the cavity in the substrate.

- 9. (Original) The structure of claim 8, comprising a plurality of trench and cavity pairs formed in the substrate.
- 10. (Original) The structure of claim 9, wherein each trench and cavity pair are formed at different levels within the substrate.
- 11. (Original) The structure of claim 9, wherein each trench and cavity pair are formed to have different cross-sectional configurations.

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- 12. (Original) The structure of claim 9, wherein each trench and cavity pair are formed to have different cross-sectional sizes.
- 13. (Original) The structure of claim 9, wherein each trench and cavity pair are formed to have a different cross-sectional size and to be formed at different levels in the substrate.

### 14-18. (Canceled)

19. (Previously Presented) A structure formed in a substrate of monolithic semiconductor material, the structure comprising:

a cavity formed in and surrounded by the monolithic semiconductor material, the monolithic semiconductor material comprising a membrane formed of the monolithic semiconductor material and an epitaxial growth on the monolithic semiconductor material that covers the cavity in the substrate, the membrane having a thickness in the range of between 1 and 3  $\mu$ m.

# 20. (Canceled)

21. (Previously Presented) The structure of claim 19, further comprising at least one trench etched into the membrane and of a depth to be in communication with the cavity.

# 22-27. (Canceled)

28. (Currently Amended) A wafer of monolithic monocrystalline semiconductor material, comprising a plurality of buried cavities, each cavity completely surrounded by said monolithic monocrystalline material and each cavity having walls and a closed bottom covered with a single coating formed of a layer of material inhibiting epitaxial

growth, the plurality of buried cavities positioned adjacent to each other and separated from each other by dividers.

- 29. (Previously Presented) The wafer of claim 28, wherein the material inhibiting epitaxial growth comprises oxide.
- 30. (Previously Presented) The wafer of claim 28, wherein the material inhibiting epitaxial growth comprises TEOS.
- 31. (Previously Presented) The wafer of 28, wherein the material inhibiting epitaxial growth comprises nitride.
- 32. (Currently Amended) A monolithic wafer of monocrystalline semiconductor material, comprising a plurality of buried-eavities trenches and cavity pairs, each trench filled with monocrystalline material, each cavity completely surrounded by said monocrystalline material and having walls and a closed bottom that are covered with a single coating that is formed of a layer of material inhibiting epitaxial growth, the plurality of buried cavities positioned at different heights within the wafer of monocrystalline semiconductor material.
- 33. (Previously Presented) The wafer of claim 32, wherein the material inhibiting epitaxial growth comprises oxide.
- 34. (Previously Presented) The wafer of claim 32, wherein the material inhibiting epitaxial growth comprises TEOS.
- 35. (Previously Presented) The wafer of 32, wherein the material inhibiting epitaxial growth comprises nitride.